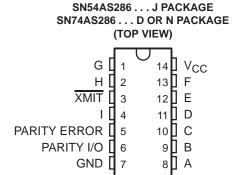
- Generate Either Odd or Even Parity for Nine Data Lines
- Cascadable for n-Bit Parity
- Direct Bus Connection for Parity Generation or Checking by Using the Parity I/O Port
- Glitch-Free Bus During Power Up/Down
- Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

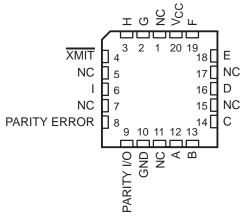
#### description

The SN54AS286 and SN74AS286 universal 9-bit parity generators/checkers feature a local output for parity checking and a 48-mA bus-driving parity input/output (I/O) port for parity generation/checking. The word-length capability is easily expanded by cascading.

The transmit (XMIT) control input is implemented specifically to accommodate cascading. When XMIT is low, the parity tree is disabled and PARITY ERROR remains at a high logic level regardless of the input levels. When XMIT is high, the parity tree is enabled. PARITY ERROR indicates a parity error when either an even number of inputs (A–I) are high and PARITY I/O is forced to a low logic level, or when an odd number of inputs are high and PARITY I/O is forced to a high logic level.



SN54AS286 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

The I/O control circuitry was designed so that the I/O port remains in the high-impedance state during power up or power down to prevent bus glitches.

The SN54AS286 is characterized for operation over the full military temperature range of  $-55^{\circ}$ C to  $125^{\circ}$ C. The SN74AS286 is characterized for operation from  $0^{\circ}$ C to  $70^{\circ}$ C.

#### **FUNCTION TABLE**

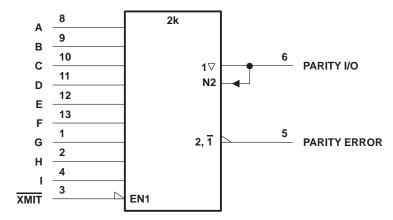
NUMBER OF INPUTS (A-I) THAT ARE HIGH	XMIT	PARITY I/O	PARITY ERROR
0, 2, 4, 6, 8	I	Н	Н
1, 3, 5, 7, 9	1	L	Н
0.0400	h	h	Н
0, 2, 4, 6, 8	h	I	L
12570	h	h	L
1, 3, 5, 7, 9	h	I	Н

h = high input level H = high output level I = low input level L = low output level

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

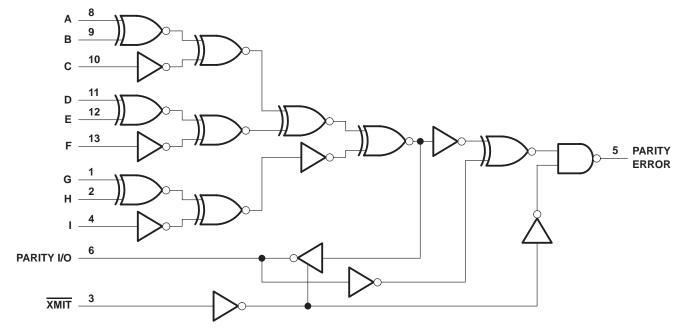


### logic symbol†



 $<sup>^\</sup>dagger$  This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.

#### logic diagram (positive logic)



Pin numbers shown are for the D, J, and N packages.

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V <sub>CC</sub>	
Input voltage, V <sub>I</sub>	
Voltage applied to a disabled 3-state output	
Operating free-air temperature range, T <sub>A</sub> : SN54AS	286 – 55°C to 125°C
SN74AS	286 0°C to 70°C
Storage temperature range	–65°C to 150°C

#### recommended operating conditions

			SI	SN54AS286			SN74AS286			
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
VCC	Supply voltage		4.5	5	5.5	4.5	5	5.5	V	
VIH	High-level input voltage		2			2			V	
VIL	Low-level input voltage				8.0			8.0	V	
		PARITY ERROR		-2				-2		
IOH	High-level output current	PARITY I/O			-12			-15	mA	
	Law law law and and an ownered	PARITY ERROR			20			20	0	
IOL	Low-level output current			32			48	mA		
TA	Operating free-air temperature		-55		125	0		70	°C	

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			TEST CONDITIONS			86	SN			
	PARAMETER	TEST CON	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT	
٧ <sub>IK</sub>		$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V
	All outputs	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V <sub>CC</sub> -2			V <sub>CC</sub> -2			
Vон			$I_{OH} = -3 \text{ mA}$	2.4	2.9		2.4	3		.,
VOH	PARITY I/O	V <sub>CC</sub> = 4.5 V	$I_{OH} = -12 \text{ mA}$	2.4						V
			$I_{OH} = -15 \text{ mA}$				2.4			
VOL	PARITY ERROR		$I_{OL} = 20 \text{ mA}$		0.35	0.5		0.35	0.5	
	PARITY I/O	V <sub>CC</sub> = 4.5 V	$I_{OL} = 32 \text{ mA}$			0.5				0.5 V
			$I_{OL} = 48 \text{ mA}$						0.5	
PARITY I/O		V 55V	V <sub>I</sub> = 5.5 V			0.1			0.1	4
l <sub>l</sub>	All other inputs	V <sub>CC</sub> = 5.5 V	V <sub>I</sub> = 7 V			0.1			0.1	mA
	PARITY I/O§	V 55V	5.5 V, V <sub>I</sub> = 2.7 V			50			50	
IН	All other inputs	$V_{CC} = 5.5 \text{ V},$				20			20	μΑ
	PARITY I/O§	V 55V	V 0.4V			-0.5			-0.5	4
All other inputs		V <sub>CC</sub> = 5.5 V,	$V_I = 0.4 V$			-0.5			-0.5	mA
IOI		V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.25 V	-30		-112	-30		-112	mA
laa	Transmit	V <sub>CC</sub> = 5.5 V			30	43		30	43	mA
Icc	Receive	ACC = 2.2 A		35 50				35	50	IIIA

<sup>‡</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.



<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

<sup>§</sup> For I/O ports, the parameters I<sub>IH</sub> and I<sub>IL</sub> include the off-state output current.

# SN54AS286, SN74AS286 9-BIT PARITY GENERATORS/CHECKERS WITH BUS-DRIVER PARITY I/O PORT SDAS050B - DECEMBER 1983 - REVISED DECEMBER 1994

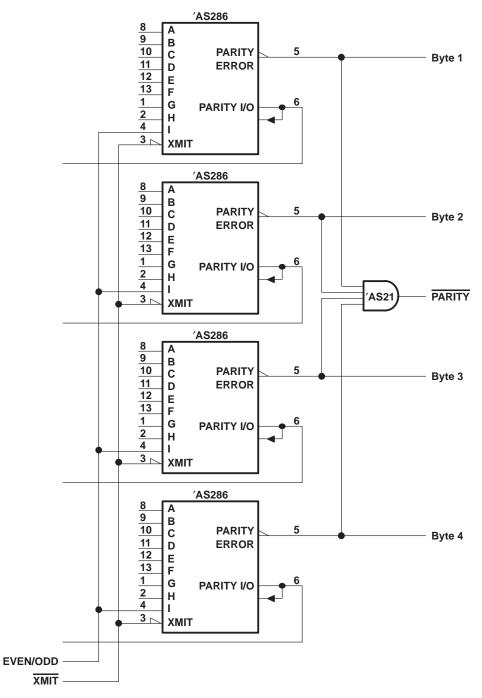
### switching characteristics (see Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>C</sub> C <sub>L</sub> R1 R2 T <sub>A</sub>	UNIT			
			SN54A MIN		SN74AS286		
				MAX	MIN	MAX	
t <sub>PLH</sub>	Any A – I	PARITY I/O		17	3	15	ns
<sup>t</sup> PHL	Ally A – I	PARITY I/O	3	15	3	14	115
<sup>t</sup> PLH	A A . I	DARITY EDDOR	3	20	3	16.5	
<sup>t</sup> PHL	Any A – I	PARITY ERROR	3	18	3	16.5	ns
<sup>t</sup> PLH	DA DITY I/O	DADITY EDDOD	3	10	3	9	
t <sub>PHL</sub>	PARITY I/O	PARITY ERROR	3	10	3	9	ns
<sup>t</sup> PZH	VA 41-	5.5.57.00		14	3	13	
t <sub>PZL</sub>	XMIT	PARITY I/O	3	17	3	16	ns
<sup>t</sup> PHZ	XMIT	PARITY I/O	3	13	3	11.5	no
<sup>t</sup> PLZ	AIVII I	FARITTI/O	3	11	3	10	ns

<sup>&</sup>lt;sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

#### **APPLICATION INFORMATION**

Figure 1 shows a 32-bit parity generator/checker with output polarity switching, parity-error detection, and parity on every byte.



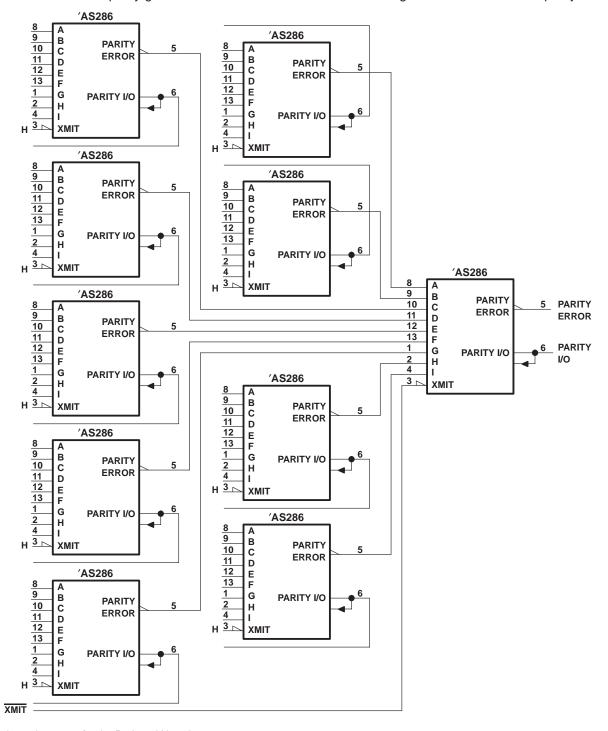
Pin numbers shown are for the D, J, and N packages.

Figure 1. 32-Bit Parity Generator/Checker



#### **APPLICATION INFORMATION**

Figure 2 shows a 90-bit parity generator/checker with XMIT on the last stage available for use with parity detection.

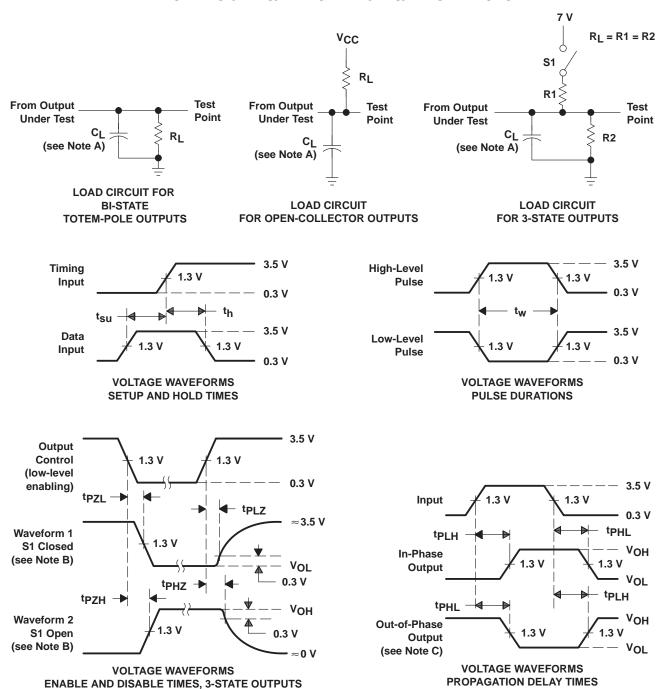


Pin numbers shown are for the D, J, and N packages.

Figure 2. 90-Bit Parity Generator/Checker With Parity-Error Detection



# PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR  $\leq$  1 MHz,  $t_r = t_f = 2$  ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 3. Load Circuits and Voltage Waveforms





www.ti.com 8-Feb-2024

#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AS286D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	AS286	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.





www.ti.com 9-Feb-2024

#### **TUBE**

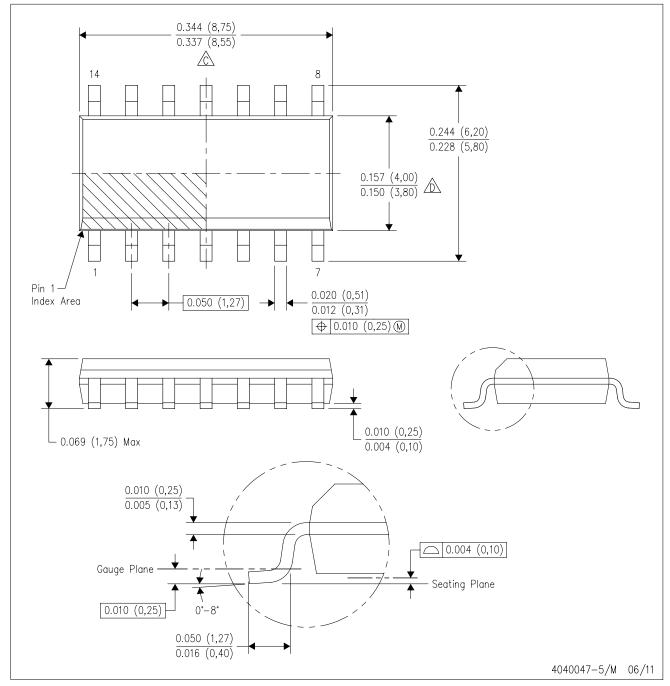


#### \*All dimensions are nominal

ĺ	Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)	
	SN74AS286D	D	SOIC	14	50	506.6	8	3940	4.32	

# D (R-PDSO-G14)

#### PLASTIC SMALL OUTLINE



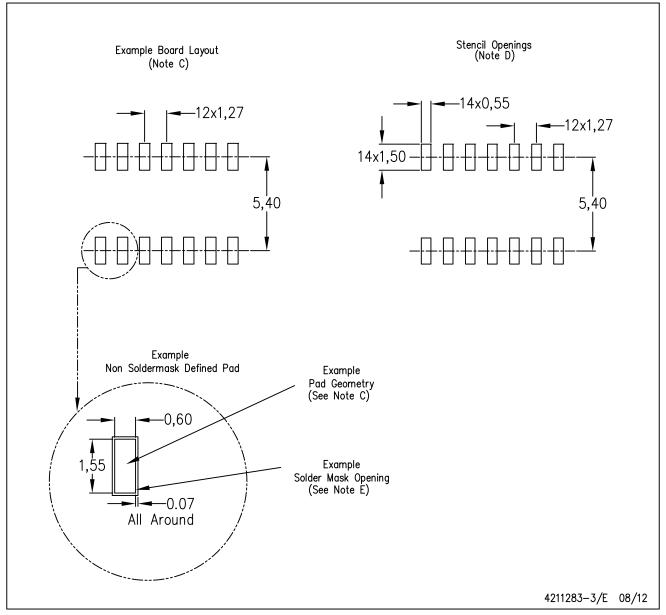
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



# D (R-PDSO-G14)

## PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



#### **IMPORTANT NOTICE AND DISCLAIMER**

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2024, Texas Instruments Incorporated